

LESD8D3.3N3T5G ESD PROTECTION DIODE

Discription

The LESD8D3.3N3T5G is designed to protect voltage sensitive components from ESD. Excellent clamping capability, low leakage, and fast response time provide best in class protection on designs that are exposed to ESD. Because of its small size, it is suited for use in cellular phones, MP3 players, digital cameras and many other portable applications where board space is at a premium.

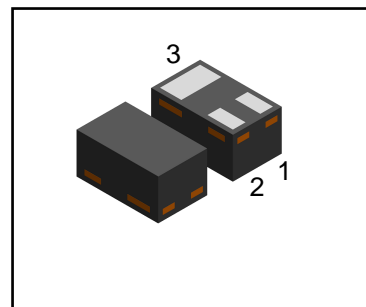
Applications

- I Cellular phones audio
- I MP3 players
- I Digital cameras
- I Portable applications
- I mobile telephone

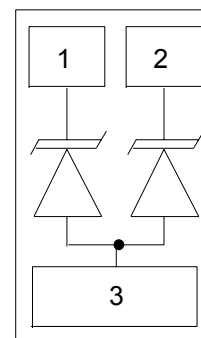
Features

- I Low Leakage
- I Response Time is Typically < 1 ns
- I ESD Rating of Class 3 per Human Body Model
- I IEC61000-4-2 Level 4 ESD Protection
- I These are Pb-Free Devices
- I We declare that the material of product compliance with RoHS requirements.

LESD8D3.3N3T5G



SOT883



Ordering information

Device	Marking	Shipping
LESD8D3.3N3T5G	F	10000/Tape&Reel

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
IEC 61000-4-2 (ESD) Air discharge		±30	kV
Contact discharge		±30	kV
ESD Voltage Per Human Body Model		16	kV
Total Power Dissipation on FR-5 Board (Note 1) @ T _A =25°C	PD	200	mW
Junction and Storage Temperature Range	T _J ,T _{STG}	-55 to 150	°C
Lead Solder Temperature – Maximum (10 Second Duration)	TL	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Rating are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

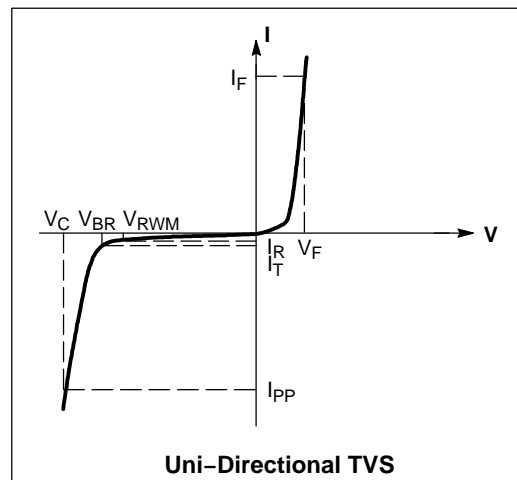
1. FR-5 = 1.0*0.75*0.62 in.

LESD8D3.3N3T5G

ELECTRICAL CHARACTERISTICS

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Working Peak Reverse Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
I_F	Forward Current
V_F	Forward Voltage @ I_F
P_{pk}	Peak Power Dissipation
C	Capacitance @ $V_R = 0$ and $f = 1.0\text{ MHz}$



ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$ unless otherwise noted, $V_F=0.9\text{V Max.}$ @ $I_F=10\text{Ma}$ for all types)

Device	V_{RWM} (V)	I_R (μA) @ V_{RWM}	V_{BR} (V) @ I_T (Note 2)	I_T (mA)	I_{PP} (A) (Note 3)	V_C (V) @ Max I_{PP} (Note 3)	P_{PK} (W) (8*20 μs)	C (pF)
	Max	Max	Min		Max	Max	Typ	Typ
LESD8D3.3N3T5G	3.3	2.5	5	1.0	6	9	54	45

2. V_{BR} is measured with a pulse test current I_T at an ambient temperature of 25°C

3. Surge current waveform per Figure 3.

LESD8D3.3N3T5G

TYPICAL CHARACTERISTICS

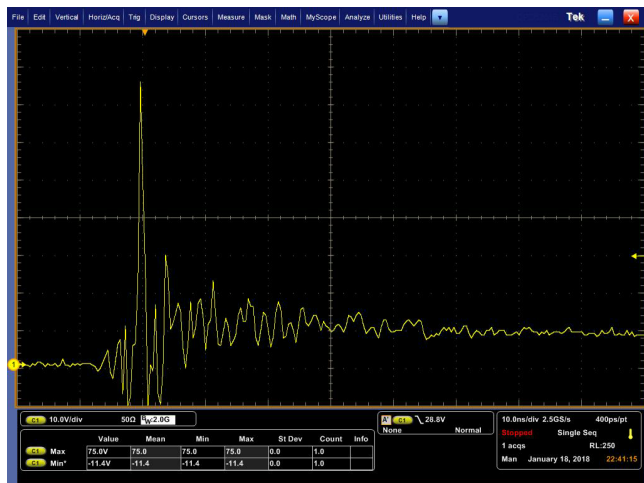


Figure 1. Positive 8kV contact per IEC 61000-4-2-LESD11D5.0T5G

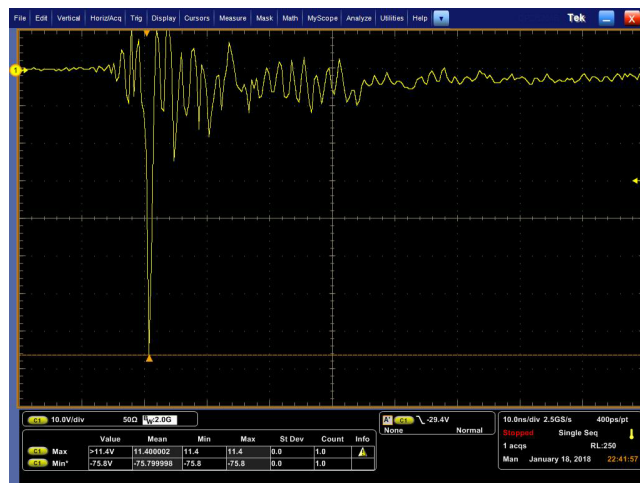


Fig 2. Negative 8kV contact per IEC 61000-4-2-LESD11D5.0T5G

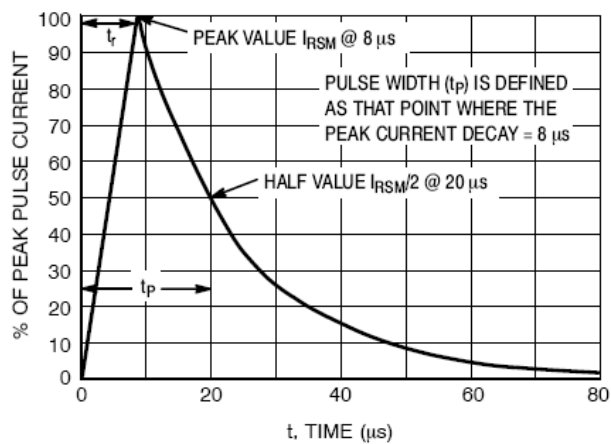
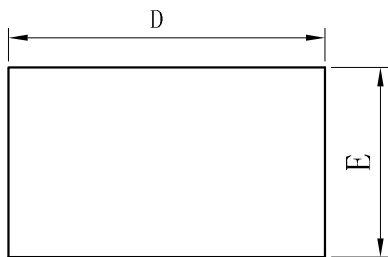


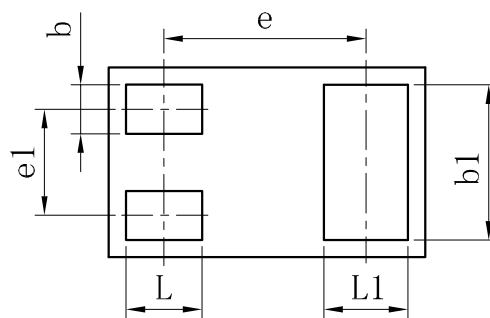
Figure 3. 8*20 μs Pulse Waveform

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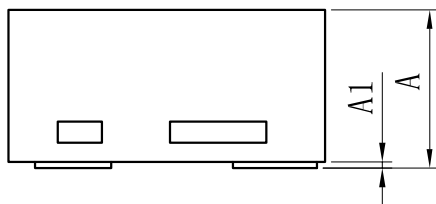
OUTLINE AND DIMENSIONS



TOP VIEW



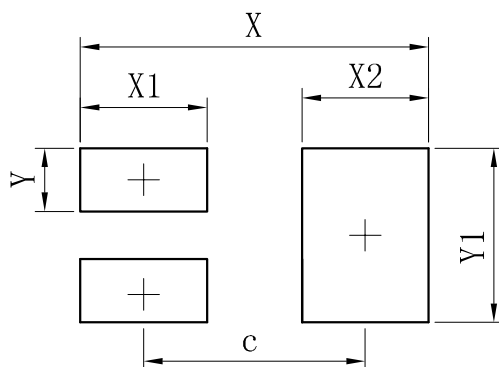
BOTTOM VIEW



SIDE VIEW

SOT883			
Dim	Min	Typ	Max
D	0.95	1.00	1.05
E	0.55	0.60	0.65
e	–	0.64	–
e1	–	0.34	–
L	0.19	0.24	0.29
L1	0.22	0.27	0.32
b	0.10	0.15	0.20
b1	0.44	0.49	0.54
A	0.43	0.48	0.53
A1	0	–	0.05
All Dimensions in mm			

SOLDERING FOOTPRINT



Dimensions	(mm)
c	0.70
X	1.10
X1	0.40
X2	0.40
Y	0.20
Y1	0.55